

RO3000® Series Circuit Materials

RO3003[™], RO3006[™], RO3010[™] and RO3035[™] High Frequency Laminates

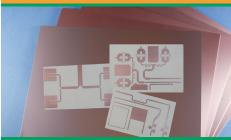
RO3000° high frequency circuit materials are ceramic-filled PTFE composites intended for use in commercial microwave and RF applications. This family of products was designed to offer exceptional electrical and mechanical stability at competitive prices.

RO3000 series laminates are ceramic-filled PTFE based circuit materials with mechanical properties that are consistent regardless of the dielectric constant selected. This allows the designer to develop multi-layer board designs that use different dielectric constant materials for individual layers, without encountering warpage or reliability problems.

RO3000 materials exhibit a coefficient of thermal expansion (CTE) in the X and Y axis of 17 ppm/°C. This expansion coefficient is matched to that of copper, which allows the material to exhibit excellent dimensional stability, with typical etch shrinkage (after etch and bake) of less than 0.5 mils per inch. The Z-axis CTE is 24 ppm/°C, which provides exceptional plated through-hole reliability, even in severe thermal environments. The dielectric constant versus temperature for RO3003™ and RO3035™ materials is very stable (Chart 1).

RO3000 series laminates can be fabricated into printed circuit boards using standard PTFE circuit board processing techniques, with minor modifications as described in the application note "Fabrication Guidelines for RO3000 Series High Frequency Circuit Materials."

Data Sheet



Features and Benefits:

Low dielectric loss (RO3003™ laminates)

• Laminates can be used in applications up to 77 GHz.

Excellent mechanical properties versus temperature

• Reliable stripline and multi-layer board constructions.

Uniform mechanical properties for a range of dielectric constants

- Ideal for multi-layer board designs with a range of dielectric constants
- Suitable for use with epoxy glass multilayer board hybrid designs

Stable dielectric constant versus temperature and frequency (RO3003 laminates)

 Ideal for band pass filters, microstrip patch antennas, and voltage controlled oscillators.

Low in-plane expansion coefficient (match to copper)

- Allows for more reliable surface mounted assemblies
- Ideal for applications sensitive to temperature change
- Excellent dimensional stability

Volume manufacturing process

Economical laminate pricing

Some Typical Applications:

- Automotive radar applications
- Global positioning satellite antennas
- Cellular telecommunications systems power amplifiers and antennas
- Patch antenna for wireless communications
- Direct broadcast satellites
- Datalink on cable systems
- Remote meter readers
- Power backplanes





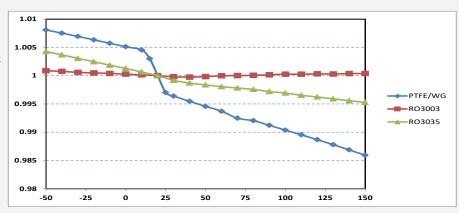




Chart 1: RO3003 and RO3035 Laminate Dielectric Constant vs. Temperature

The data in Chart 1 demonstrates the excellent stability of dielectric constant over temperature for RO3003 & RO3035 laminates, including the elimination of the step change in dielectric constant, which occurs near room temperature with PTFE glass materials.

The data in Chart 2 shows the



distribution of dissipation factor for RO3003 and RO3035 materials.

Test Method: IPC-TM-650 2.5.5.5 Condition: 10 GHz 23° C

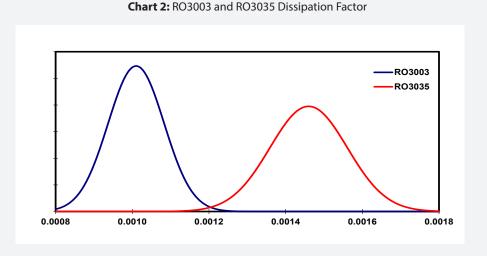
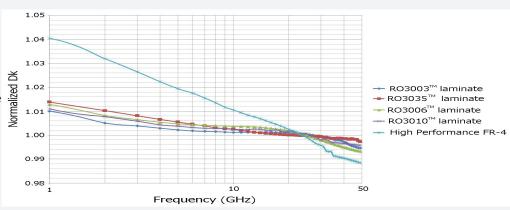


Chart 3: Normalized Dk vs. Frequency using microstrip differential phase length method 50 ohm microstrip circuits based on ~20mil thick laminates

Chart 3 demonstrates the stability of dielectric constant for RO3000 series products over frequency. This stability simplifies the design of broadband components as well as allowing the materials to be used in a wide range of applications over a very broad range of frequencies.



100 S. Roosevelt Avenue, Chandler, AZ 85226 Tel: 480-961-1382 Fax: 480-961-4533 www.rogerscorp.com





Property	Typical Value ⁽¹⁾				Diversities	1124	Condition	To at Marthaul
	RO3003	RO3035	RO3006	RO3010	Direction	Direction Unit	Condition	Test Method
Dielectric Constant, $\varepsilon_{_{\rm r}}$ Process	3.00 ± 0.04	3.50 ± 0.05	6.15 ± 0.15	10.2 ± 0.30	Z	-	10 GHz 23°C	IPC-TM-650 2.5.5.5 Clamped Stripline
$^{(2)}$ Dielectric Constant, $\varepsilon_{_{\rm r}}$ Design	3.00	3.60	6.50	11.20	Z	-	8 GHz - 40 GHz	Differential Phase Length Method
Dissipation Factor, $\tan\delta$	0.0010	0.0015	0.0020	0.0022	Z	-	10 GHz 23°C	IPC-TM-650 2.5.5.5
Thermal Coefficient of $\epsilon_{_{\! r}}$	-3	-45	-262	-395	Z	ppm/°C	10 GHz -50 to 150°C	IPC-TM-650 2.5.5.5
Dimensional Stability	-0.06 0.07	-0.11 0.11	-0.27 -0.15	-0.35 -0.31	X Y	mm/m	COND A	IPC TM-650 2.2.4
Volume Resistivity	10 ⁷	10 ⁷	10⁵	10 ⁵		MΩ•cm	COND A	IPC 2.5.17.1
Surface Resistivity	10 ⁷	10 ⁷	10⁵	10⁵		ΜΩ	COND A	IPC 2.5.17.1
Tensile Modulus	930 823	1025 1006	1498 1293	1902 1934	X Y	MPa	23°C	ASTM D638
Moisture Absorption	0.04	0.04	0.02	0.05	-	%	D48/50	IPC-TM-650 2.6.2.1
Specific Heat	0.9		0.86	0.8		J/g/K		Calculated
Thermal Conductivity	0.50	0.50	0.79	0.95	-	W/m/K	50°C	ASTM D5470
Coefficient of Thermal Expansion (-55 to 288 °C)	17 16 25	17 17 24	17 17 24	13 11 16	X Y Z	ppm/°C	23°C/50% RH	IPC-TM-650 2.4.41
Td	500	500	500	500		°C TGA		ASTM D3850
Density	2.1	2.1	2.6	2.8		gm/cm³	23°C	ASTM D792
Copper Peel Strength	12.7	10.2	7.1	9.4		lb/in	1 oz. EDC After Solder Float	IPC-TM-2.4.8
Flammability	V-0	V-0	V-0	V-0				UL 94
Lead Free Process Compatible	YES	YES	YES	YES				

RoHS Compliant

NOTES:

⁽¹⁾ Typical values are a representation of an average value for the population of the property. For specification values contact Rogers Corporation.

⁽²⁾ The design Dk is an average number from several different tested lots of material and on the most common thickness/s. If more detailed information is required, please contact Rogers Corporation or refer to Rogers' technical papers in the Roger Technology Support Hub available at http://www.rogerscorp.com/acm/technology.





Standard Thickness	Standard Panel Size	Available Copper Cladding			
RO3003/RO3035:	12" X 18" (305 X 457mm)	1/4 oz. (9μm) electrodeposited copper foil (HQ/HQ) 1/2 oz. (17μm) electrodeposited copper foil (HH/HH) 1 oz. (35μm) electrodeposited copper foil (H1/H1)			
0.005" (0.13mm) 0.010" (0.25mm) 0.020" (0.50mm) 0.030" (0.75mm) 0.060" (1.52mm)	24" X 18" (610 X 457mm)				
		2 oz. (70μm) electrodeposited copper foil (H2/H2)			
		½ oz. (17μm) reverse treated electrodeposited cu foil (SH/SH) 1 oz. (35μm) reverse treated electrodeposited cu foil (S1/S1)			
RO3006/RO3010:					
0.005" (0.13mm) 0.010" (0.25mm)		2 oz. (70µm) reverse treated electrodeposited cu foil (S2/S2)			
0.025" (0.64mm)					
0.050" (1.28mm)		RO3003 & RO3035 laminates also available with $\frac{1}{2}$, 1 and 2 oz. rolled copper foil			
		RO3003 5 mil thick laminates also available with 6 oz. rolled copper foil			
		and 0.040" rolled copper plate			
		Other claddings may be available. Contact customer service.			

The information in this data sheet is intended to assist you in designing with Rogers' circuit materials. It is not intended to and does not create any warranties express or implied, including any warranty of merchantability or fitness for a particular purpose or that the results shown on this data sheet will be achieved by a user for a particular purpose. The user should determine the suitability of Rogers' circuit materials for each application.

These commodities, technology and software are exported from the United States in accordance with the Export Administration regulations. Diversion contrary to U.S. law prohibited.

The Rogers' logo, Helping power, protect, connect our world, RO3000, RO3003, RO3006, R03010 and RO3035 are trademarks of Rogers Corporation or one of its subsidiaries.

©2019 Rogers Corporation, Printed in U.S.A., All rights reserved. Revised 1438 071119 **Publication** #92-130

Advanced Connectivity Solutions